MGV252012S1R0M-10

PHYSICAL DIMENSIONS:

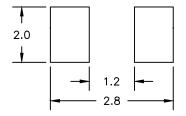
A 2.50 ± 0.20

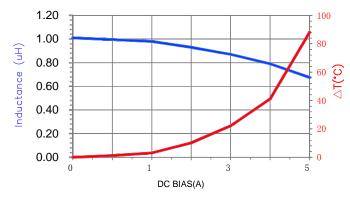
 $B 2.00 \pm 0.20$

C 1.20 Max.

 $D = 0.60 \pm 0.30$

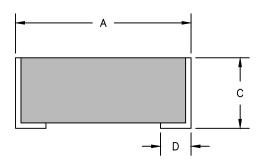
LAND PATTERNS FOR REFLOW SOLDERING



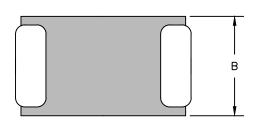


ELECTRICAL SPECIFICATION @ 25°C

	Min	Norm	Max	
INDUCTANCE (uH) L @ 1MHz/1mA ±20%	0.80	1.00	1.10	
DCR (Ω)		0.036	0.044	
Saturation Current Isat (A)		4.30	3.80	
Heating Current Irms (A)		3.90	3.30	







NOTES:

- 1. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 2. TERMINATION FINISH IS 100% TIN.
- 3. OPERATING TEMPERATURE RANGE: $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$.
- 4. STORAGE TEMPERATURE RANGE: -50°C ~ +125°C .
- 5. ISat MEANS THAT MAX DC CURRENT WILL CAUSE A PROXIMATELY 30% INDUCTANCE REDUCTION FROM INITIAL VALUE.
- 6. Irms MEANS THAT MAX DC CURRENT WILL CAUSE PROXIMATELY 40°C TEMPERATURE RISE FROM 25±5°C AMBIENT.

DIMENSIONS ARE IN mm.		This print is the property of Laird						
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